Fuji Electric

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FMW60N025S2HF

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FUJI POWER MOSFET

Super J MOS® S2 series

N-Channel enhancement mode power MOSFET

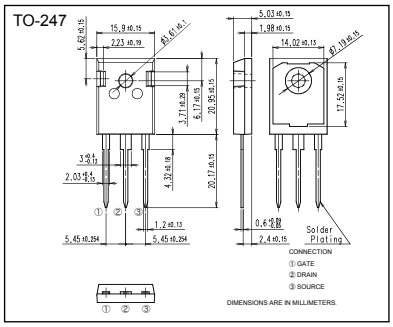
Features

Pb-free lead terminal
RoHS compliant
uses Halogen-free molding compound

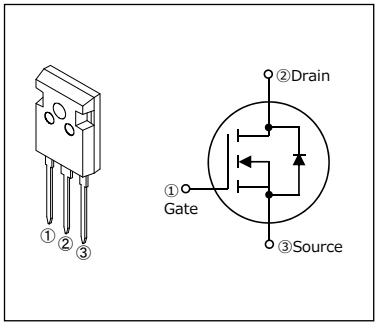
Applications

For switching

Outline Drawings [mm]



Equivalent circuit schematic



Absolute Maximum Ratings at T_c=25°C (unless otherwise specified)

Parameter	Symbol	Characteristics	Unit	Remarks
Drain-Source Voltage	V_{DS}	600	V	
	V_{DSX}	600	V	V_{GS}=-30V
Continuous Drain Current	I_D	95.5	A	Tc=25°C Note*1
		60.4	A	Tc=100°C Note*1
Pulsed Drain Current	I_{DP}	286.5	A	Note *1
Gate-Source Voltage	V_{GS}	±30	V	
Non-Repetitive Maximum Avalanche Current	I_{AS}	8.5	A	Note *2
Non-Repetitive Maximum Avalanche Energy	E_{AS}	6074	mJ	Note *3
Maximum Drain-Source dV/dt	dV_{DS}/dt	50	V/ns	V_{DS}≤ 600V
Continuous Diode Forward Current	I_{SD}	95.5	A	Tc=25°C Note*1
		60.4	A	Tc=100°C Note*1
Pulsed Diode Forward Current	I_{SDP}	286.5	A	Note *1
Peak Diode Recovery dV/dt	dV/dt	15	V/ns	Note *4
Peak Diode Recovery -di/dt	-di/dt	100	A/μs	Note *5
Maximum Power Dissipation	P_D	2.50	W	T_a=25°C
		575		T_c=25°C
Operating and Storage Temperature range	T_{ch}	150	°C	
	T_{stg}	-55 to +150	°C	

Note *1 : Limited by maximum channel temperature.
Note *2 : T_{ch}≤150°C, See Fig.1 and Fig.2
Note *3 : Starting T_{ch}=25°C, I_{AS}=5.1A, L=428mH, V_{DD}=60V, R_G=50Ω, See Fig.1 and Fig.2
E_{AS} limited by maximum channel temperature and avalanche current.
Note *4 : I_{SD}≤95.5A, -di/dt≤100A/μs, $V_{DS\ peak}$≤600V, T_{ch}≤150°C.
Note *5 : I_{SD}≤95.5A, dV/dt≤15V/ns, $V_{DS\ peak}$≤600V, T_{ch}≤150°C.

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OCTOBER 2016

Electrical Characteristics at T_c=25°C (unless otherwise specified)

• Static Ratings

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA		600	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} I_D=6.07mA		2.5	4.0	4.5	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=600V V_{GS}=0V	T_{ch}=25°C	-	-	25	μA
		V_{DS}=480V V_{GS}=0V	T_{ch}=125°C	-	-	250	
Gate-Source Leakage Current	I_{GSS}	V_{DS}=0V V_{GS}= ± 30V		-	10	100	nA
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS}=10V I_D=47.8A		-	0.0230	0.0254	Ω
Gate resistance	R_G	f=1MHz, open drain		-	2.7	-	Ω

• Dynamic Ratings

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Transconductance	g_{fs}	V_{DS}=25V I_D=47.8A	38	77	-	S
Input Capacitance	C_{iss}	V_{DS}=400V V_{GS}=0V f=250kHz	-	5700	-	pF
Output Capacitance	C_{oss}		-	192	-	
Reverse Transfer Capacitance	C_{rss}		-	22.2	-	
Effective output capacitance, energy related (Note *6)	$C_{o(er)}$	V_{DS}=0…400V V_{GS}=0V	-	440	-	
Effective output capacitance, time related (Note *7)	$C_{o(tr)}$	V_{DS}=0…400V V_{GS}=0V I_D=constant	-	1865	-	
Turn-On Time	$t_{d(on)}$	V_{DD}=400V, V_{GS}=10V I_D=47.8A, R_G=5.6Ω See Fig.3 and Fig.4	-	38	-	ns
	t_r		-	170	-	
Turn-Off Time	$t_{d(off)}$		-	193	-	
	t_f		-	25	-	
Total Gate Charge	Q_G	V_{DD}=400V, V_{GS}=10V I_D=95.5A See Fig.5	-	222	-	nC
Gate-Source Charge	Q_{GS}		-	76	-	
Gate-Drain Charge	Q_{GD}		-	101	-	
Drain-Source crossover Charge	Q_{SW}		-	49	-	

Note *6 : $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 400V.
Note *7 : $C_{o(tr)}$ is a fixed capacitance that gives the same charging times as C_{oss} while V_{DS} is rising from 0 to 400V.

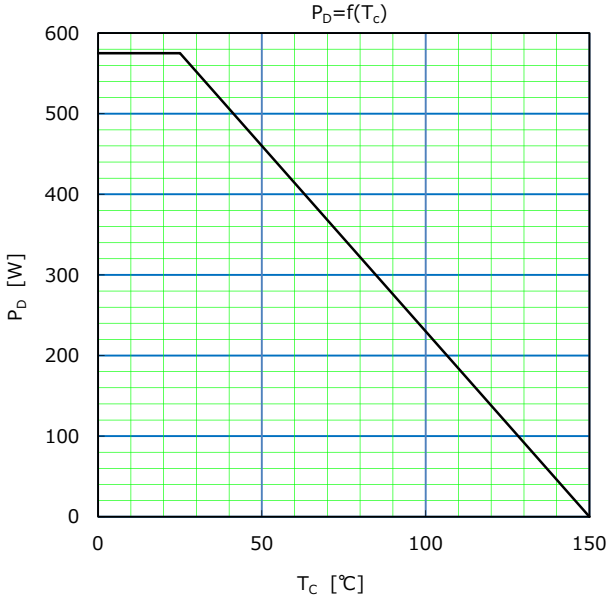
• Reverse Diode

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Diode Forward On-Voltage	V_{SD}	I_{SD}=95.5A, V_{GS}=0V T_{ch}=25°C	-	0.95	1.35	V
Reverse Recovery Time	t_{rr}	V_{DD}=400V, I_{SD}=95.5A -di/dt=100A/μs T_{ch}=25°C See Fig.6 and Fig.7	-	490	-	ns
Reverse Recovery Charge	Q_{rr}		-	11	-	μC
Peak Reverse Recovery Current	I_{rp}		-	44	-	A

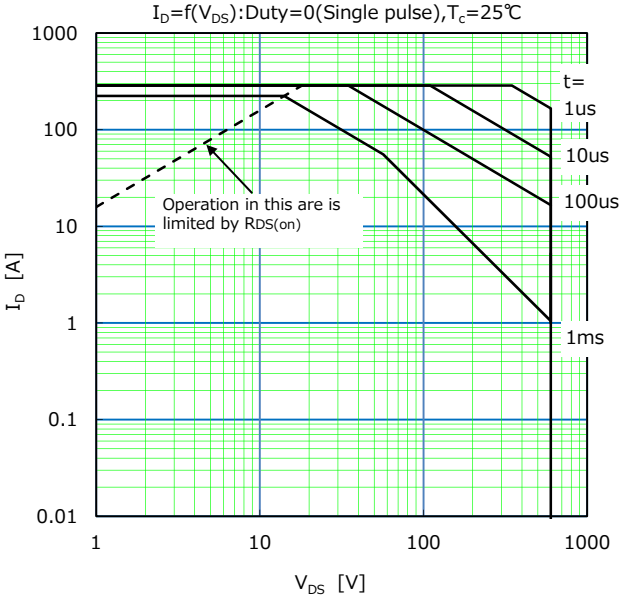
Thermal Resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Channel to Case	$R_{th(ch-c)}$	-	-	0.217	°C/W
Channel to Ambient	$R_{th(ch-a)}$	-	-	50	°C/W

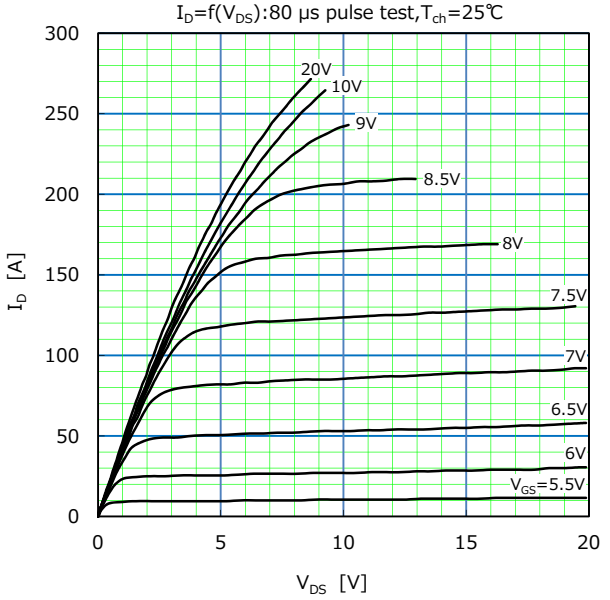
Allowable Power Dissipation
$P_D=f(T_c)$



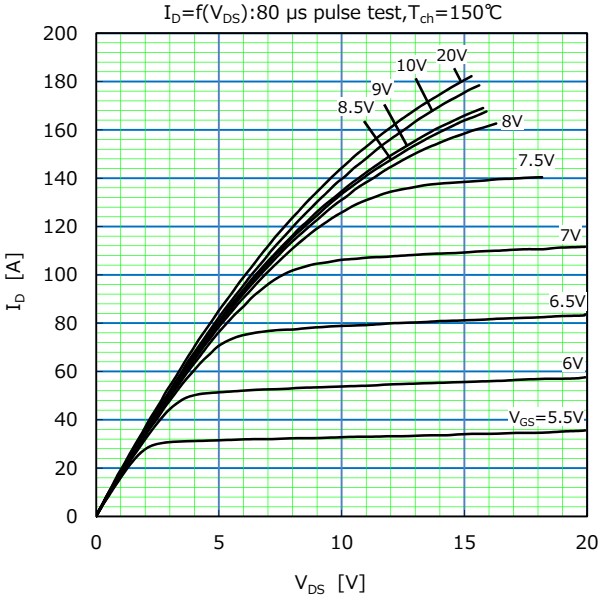
Safe Operating Area
$I_D=f(V_{DS})$:Duty=0(Single pulse),T_c=25℃



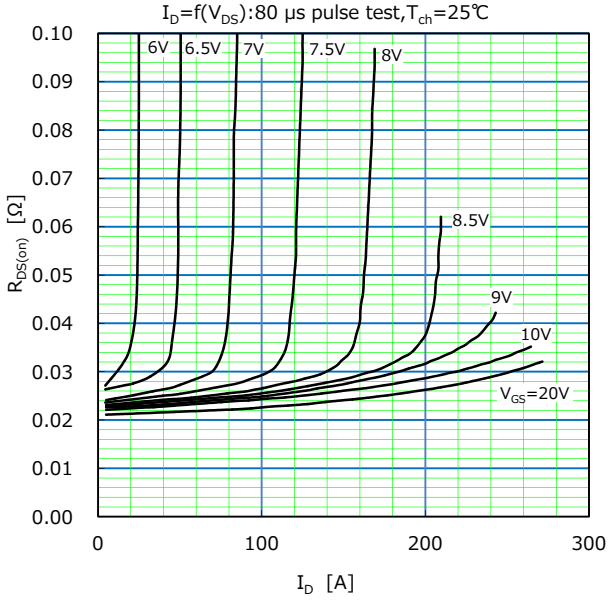
Typical Output Characteristics
$I_D=f(V_{DS})$:80 μs pulse test,T_{ch}=25℃



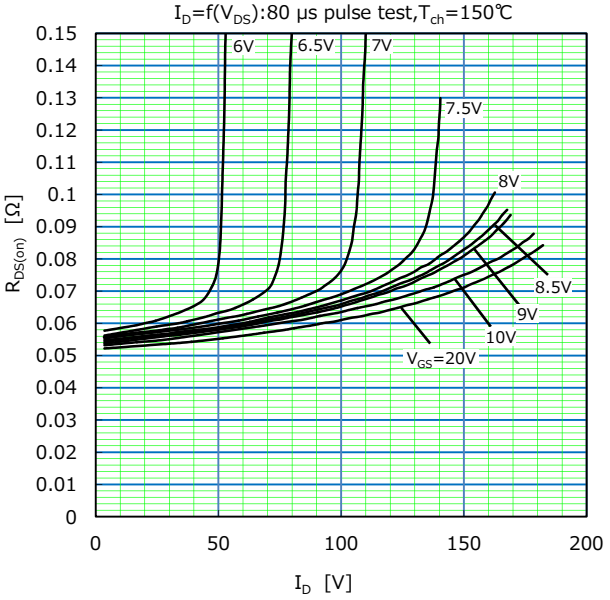
Typical Output Characteristics
$I_D=f(V_{DS})$:80 μs pulse test,T_{ch}=150℃



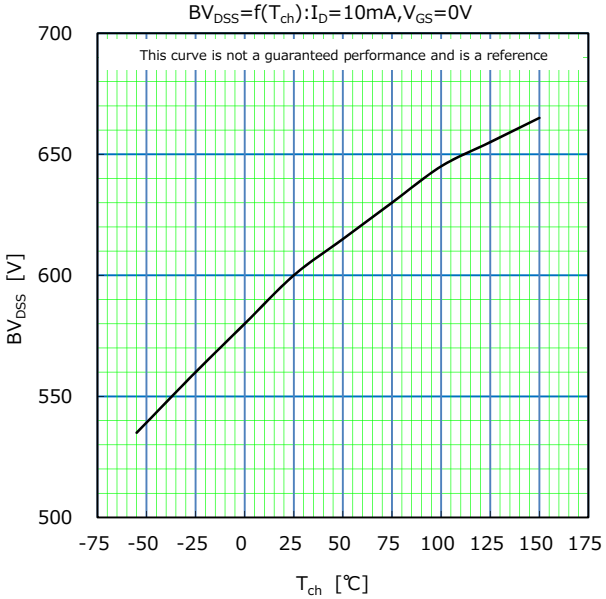
Typical Output Characteristics
$I_D=f(V_{DS})$:80 μs pulse test,T_{ch}=25℃



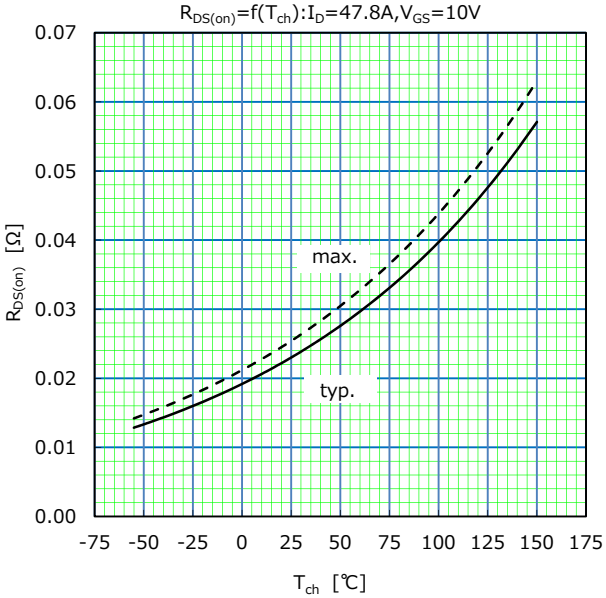
Typical Output Characteristics
$I_D=f(V_{DS})$:80 μs pulse test,T_{ch}=150℃



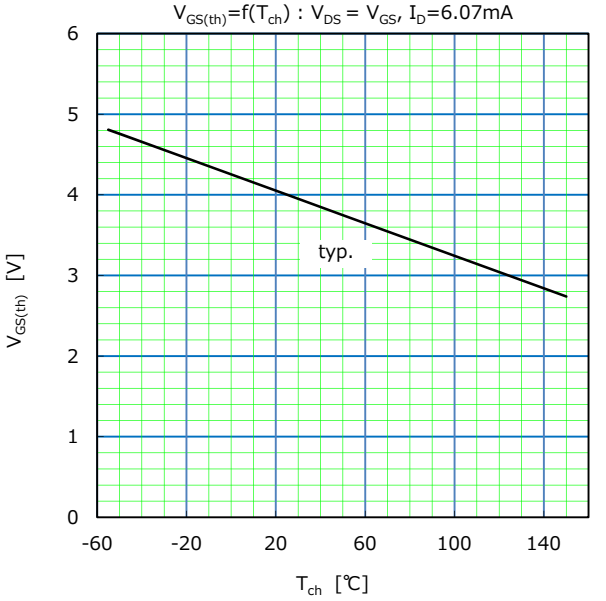
Drain-Source Breakdown Voltage
$BV_{DSS}=f(T_{ch}):I_D=10mA,V_{GS}=0V$



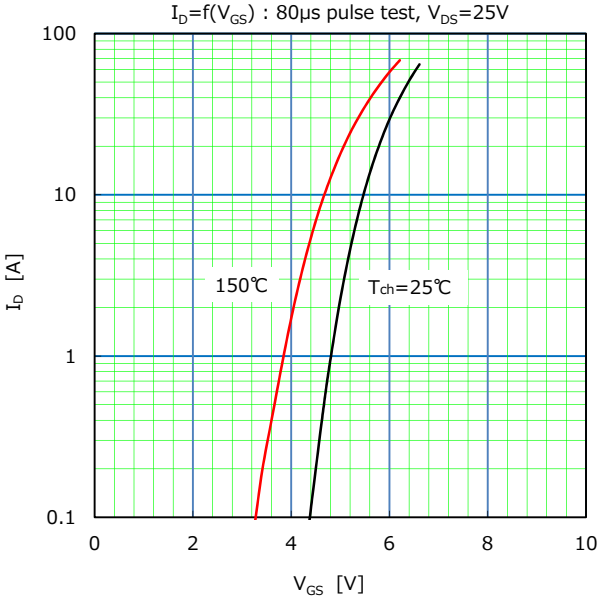
Drain-Source On-state Resistance
$R_{DS(on)}=f(T_{ch}):I_D=47.8A,V_{GS}=10V$



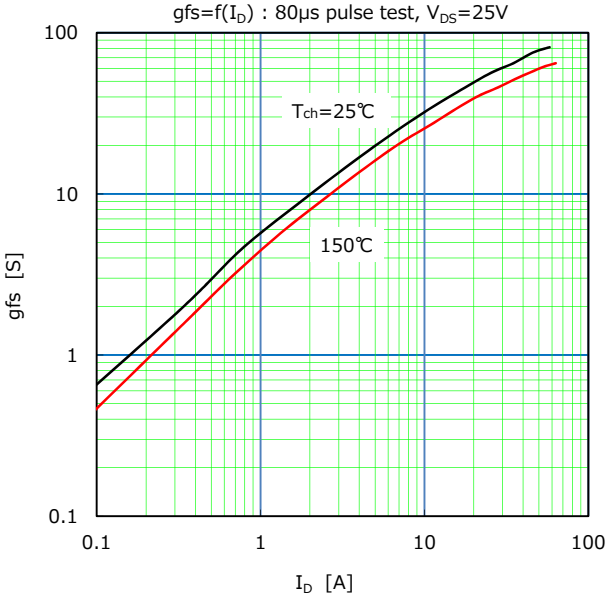
Gate Threshold Voltage vs. T_{ch}
$V_{GS(th)}=f(T_{ch})$: $V_{DS}=V_{GS}$, $I_D=6.07mA$



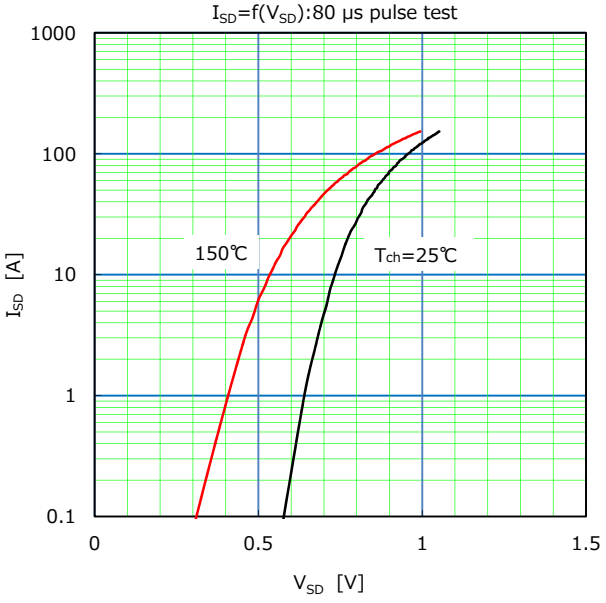
Typical Transfer Characteristic
$I_D=f(V_{GS})$: 80μs pulse test, $V_{DS}=25V$



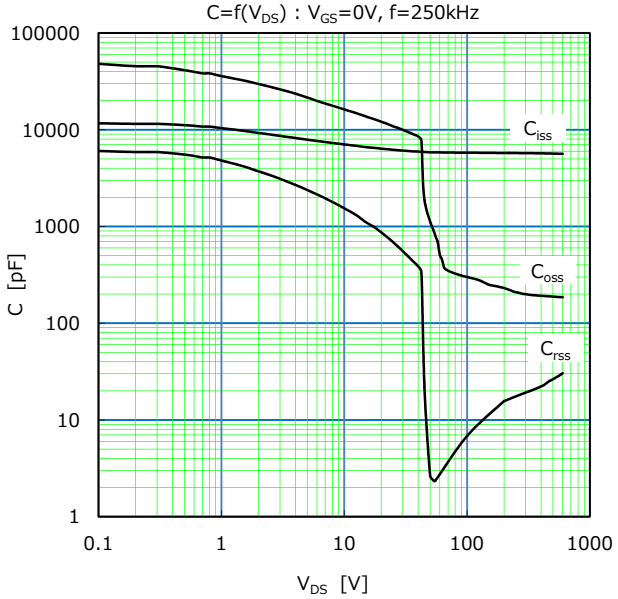
Typical Transconductance
$gfs=f(I_D)$: 80μs pulse test, $V_{DS}=25V$



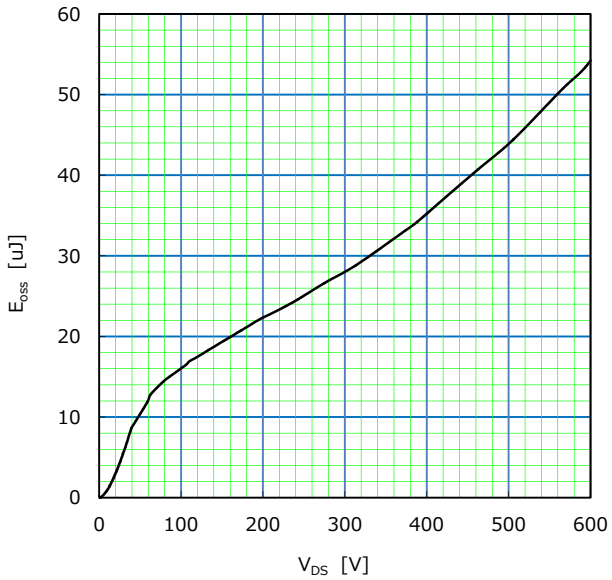
Typical Forward Characteristics of Reverse Diode
$I_{SD}=f(V_{SD})$:80 μs pulse test



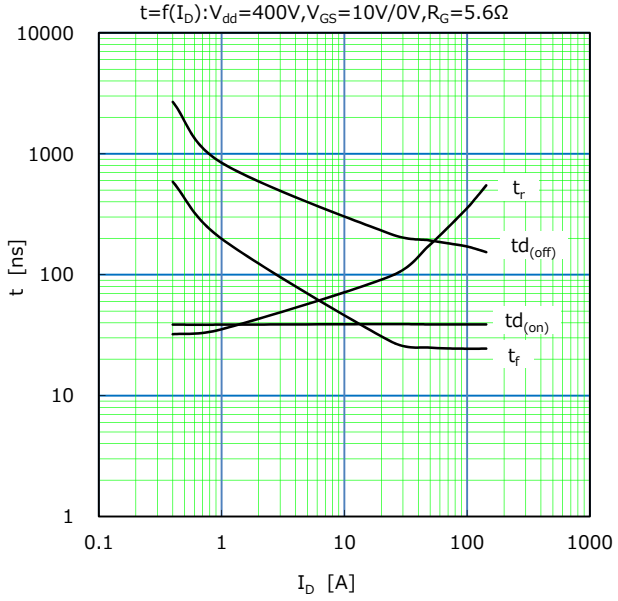
Typical Capacitance
C=f(V_{DS}) : V_{GS}=0V, f=250kHz



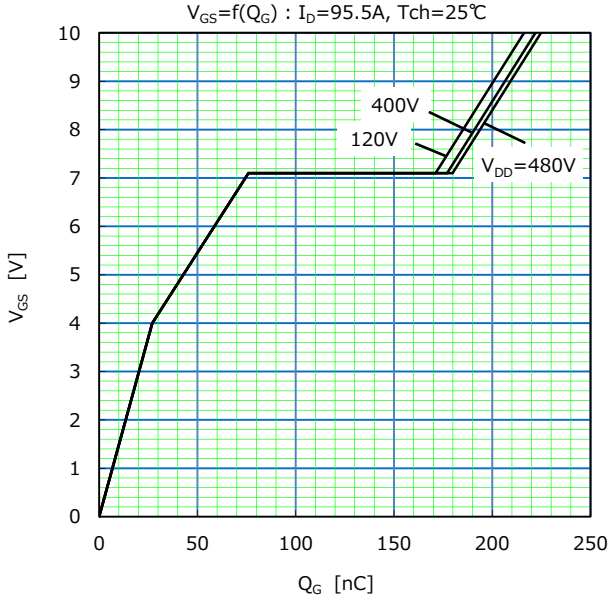
Typical C_{oss} stored energy



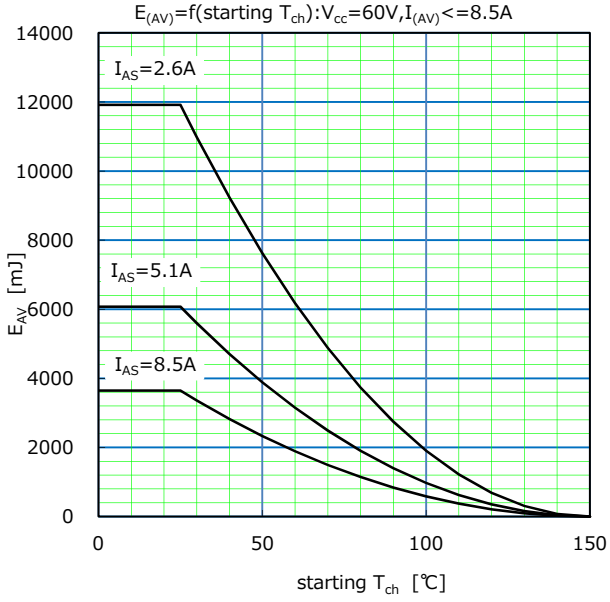
Typical Switching Characteristics vs. I_D T_{ch}=25℃
t=f(I_D):V_{dd}=400V,V_{GS}=10V/0V,R_G=5.6Ω



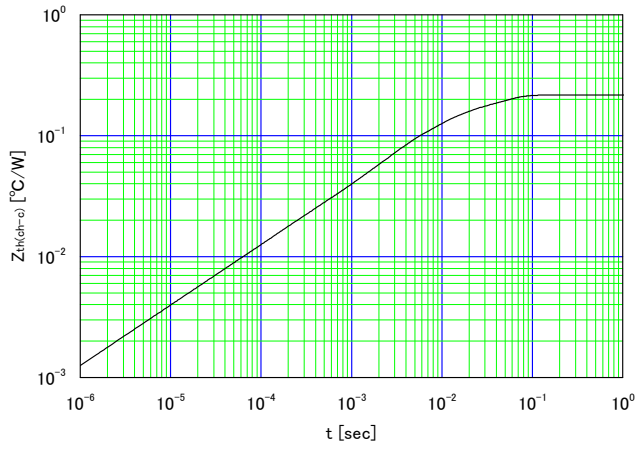
Typical Gate Charge Characteristics
V_{GS}=f(Q_G) : I_D=95.5A, Tch=25℃



Maximum Avalanche Energy vs. startingT_{ch}
$E_{(AV)}$=f(starting T_{ch}):V_{cc}=60V,$I_{(AV)}$<=8.5A



Transient Thermal Impedance
$Z_{th(ch-c)}$=f(t):D=0



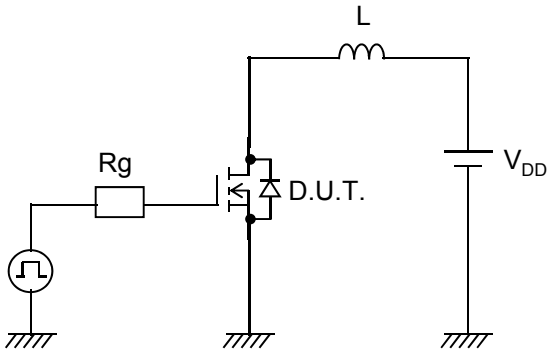


Fig.1 Avalanche Test circuit

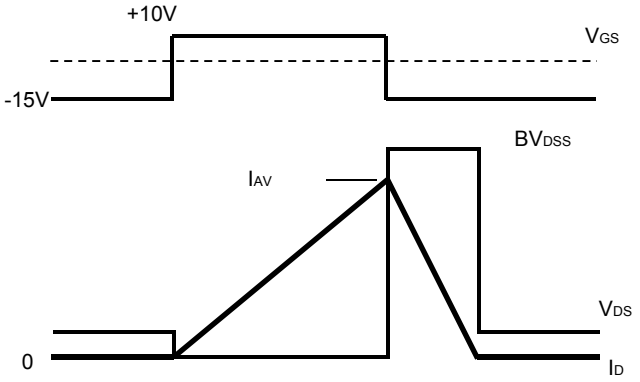


Fig.2 Operating waveforms of Avalanche Test

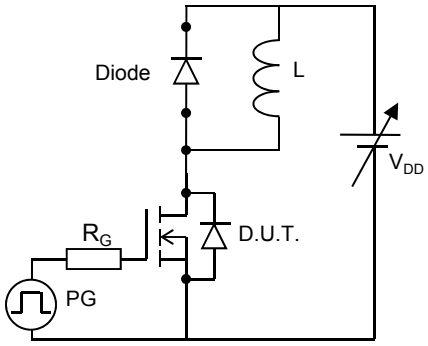


Fig.3 Switching Test circuit

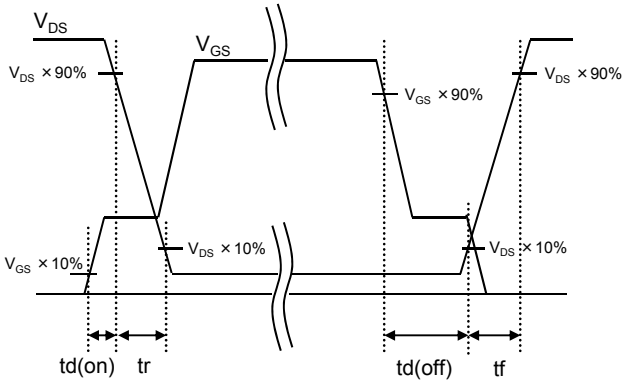


Fig.4 Operating waveform of Switching Test

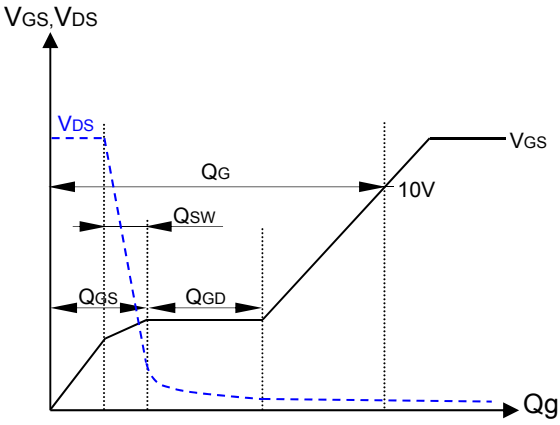


Fig.5 Operating waveform of Gate charge Test

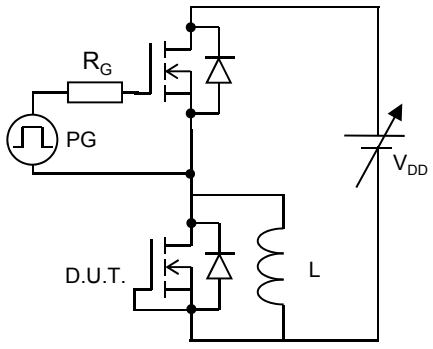


Fig.6 Reverse recovery Test circuit

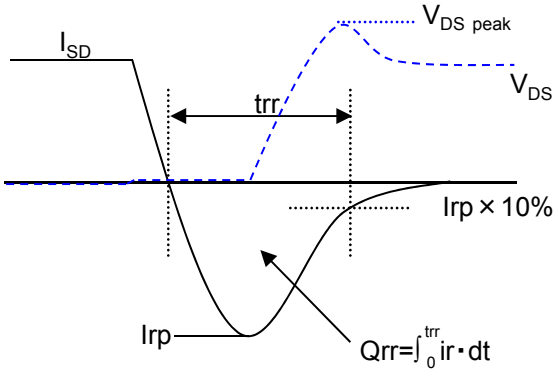
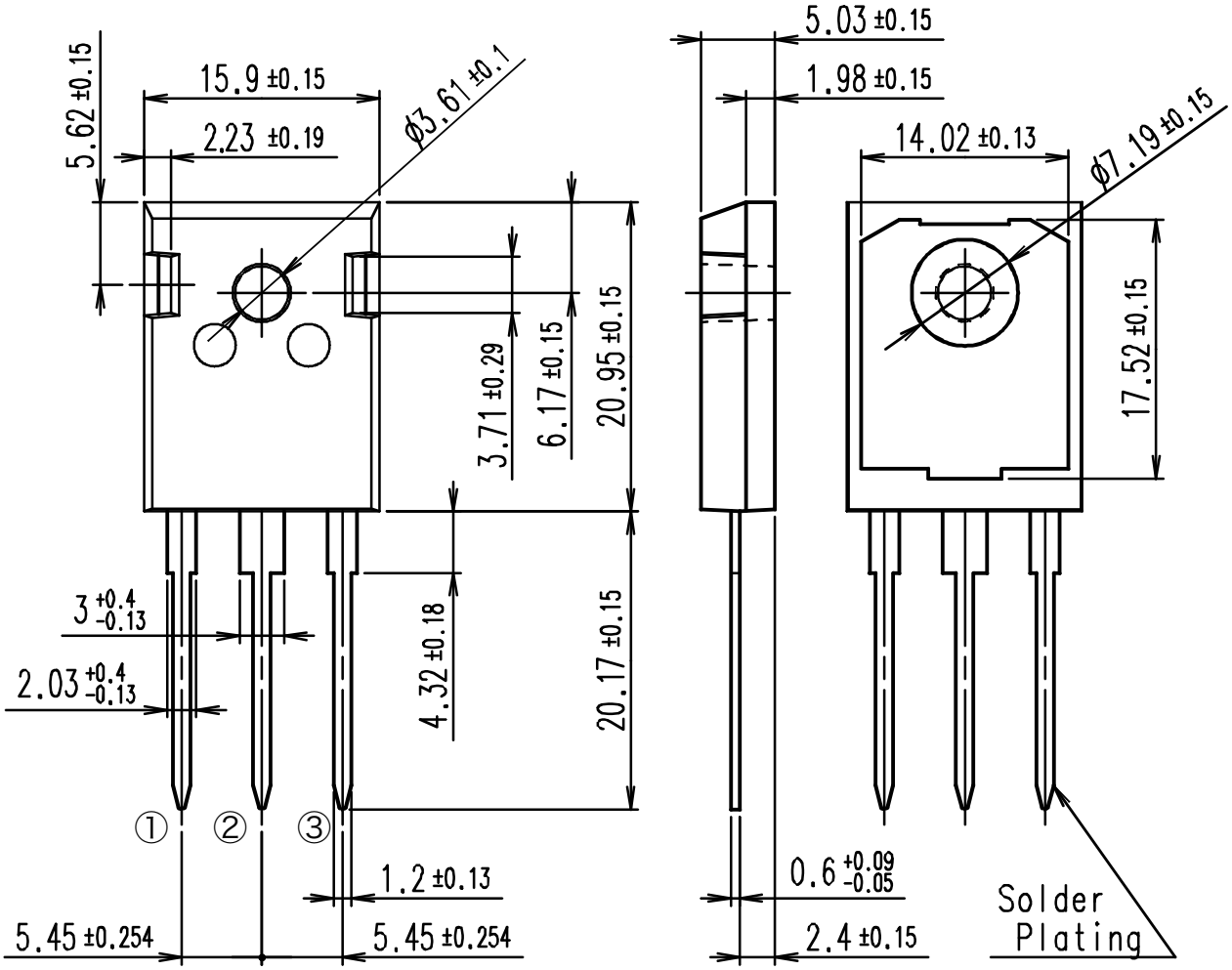
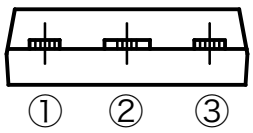


Fig.7 Operating waveform of Reverse recovery Test

Outview: TO-247 Package





CONNECTION

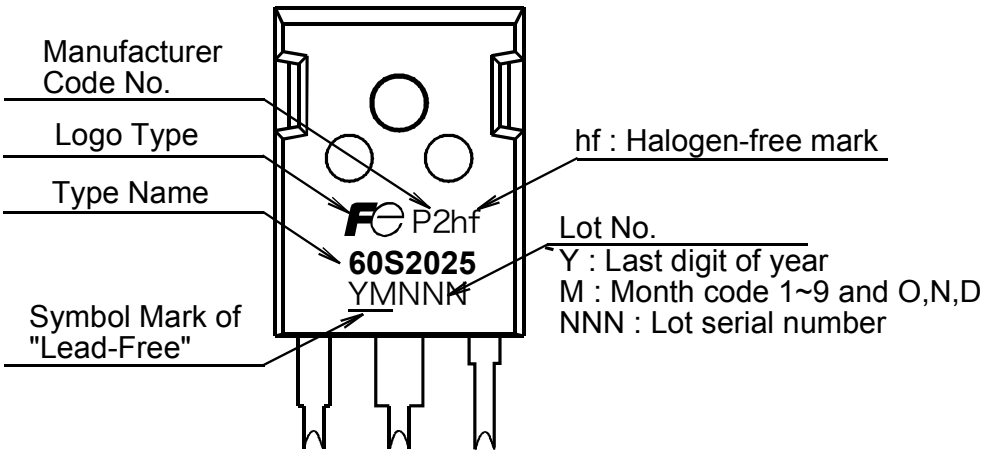
① GATE

② DRAIN

③ SOURCE

DIMENSIONS ARE IN MILLIMETERS.

Marking



* The font (font type,size) and the logo type size might be actually different.

WARNING

1. This Catalog contains the product specifications, characteristics, data, materials, and structures as of October 2016.
The contents are subject to change without notice for specification changes or other reasons. When using a product listed in this Catalog, be sur to obtain the latest specifications.

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• Machine tools • Audiovisual equipment • Electrical home appliances • Personal equipment • Industrial robots etc.

5. If you need to use a product in this Catalog for equipment requiring higher reliability than normal, such as for the equipment listed below, it is imperative to contact Fuji Electric Co., Ltd. to obtain prior approval. When using these products for such equipment, take adequate measures such as a backup system to prevent the equipment from malfunctioning even if a Fuji's product incorporated in the equipment becomes faulty.
• Transportation equipment (mounted on cars and ships) • Trunk communications equipment
• Traffic-signal control equipment • Gas leakage detectors with an auto-shut-off feature
• Emergency equipment for responding to disasters and anti-burglary devices • Safety devices
• Medical equipment

6. Do not use products in this Catalog for the equipment requiring strict reliability such as the following and equivalents to strategic equipment (without limitation).
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• Submarine repeater equipment

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